



**SEMICONDUCTOR  
TECHNOLOGIES &  
INSTRUMENTS**

www.stigp.com

# tSort

## Intelligent, Intuitive And High Speed Die Sorter

tSort is a high speed rotary die sorter that offers a complete turnkey solution for wafer level packaging. Using STI's proprietary vision inspection technology, tSort provides a state of the art vision algorithm for inspecting wafer level chip scale packages with unsurpassed accuracy and reliability.



### Features:

- Inspects Bump and Pad WLCSP Devices
- True Measurement Method
- 2D & 3D Wafer Bump Metrology Provide Coplanarity Measurement
- Bump Damage Detection Metrology
- Edge and Corner-chipping Inspection
- Active Die Surface Inspection
- Carbon Coated Die Inspection
- 2D Matrix and OCR Ready
- Post Seal Inspection
- Seal Line Quality Check
- Automated Accuracy Check
- Colour Inspection Solution
- Automated Dual Taper
- Skeleton Wafer Verification
- Side Wall Micro Crack Inspection
- Wafer Reconstruction
- Auto E-Pin Verification
- IR Inspection Capability for Post Seal, Back Side & Side Wall